



## 4N65Z

Power MOSFET

### 4A, 650V N-CHANNEL POWER MOSFET

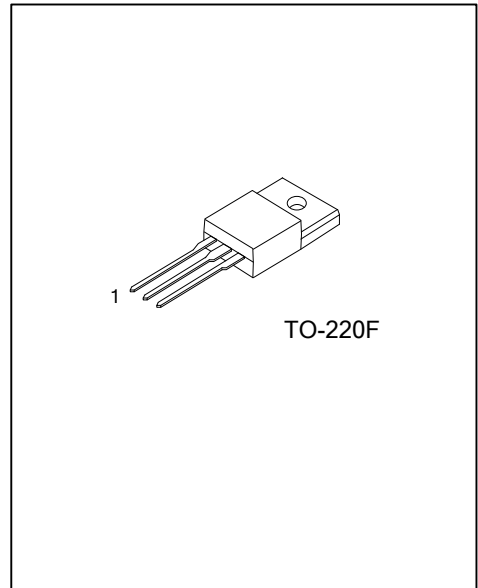
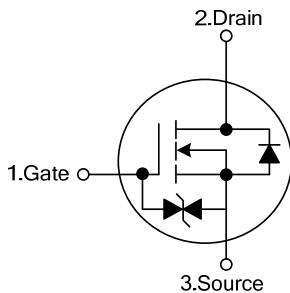
#### DESCRIPTION

The UTC **4N65Z** is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristic. This power MOSFET is usually used in high speed switching applications including power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

#### FEATURES

- \*  $R_{DS(ON)} = 2.5\Omega @V_{GS} = 10V$
- \* Ultra Low Gate Charge ( typical 15 nC )
- \* Low Reverse Transfer Capacitance (  $C_{RSS} = \text{Typical } 8.0 \text{ pF}$  )
- \* Fast Switching Capability
- \* Avalanche Energy Specified
- \* Improved dv/dt Capability, High Ruggedness

#### SYMBOL



#### ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
4N65ZL-TF3-T	4N65ZG-TF3-T	TO-220F	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>4N65ZL-TF3-T</p>	<p>(1) T: Tube</p> <p>(2) TF3: TO-22F</p> <p>(3) G: Halogen Free, L: Lead Free</p>
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■ ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	RATINGS	UNIT
Drain-Source Voltage	$V_{DSS}$	650	V
Gate-Source Voltage	$V_{GSS}$	$\pm 30$	V
Avalanche Current (Note 2)	$I_{AR}$	4.4	A
Drain Current	Continuous	$I_D$	4.0
	Pulsed (Note 2)	$I_{DM}$	16
Avalanche Energy	Single Pulsed (Note 3)	$E_{AS}$	260
	Repetitive (Note 2)	$E_{AR}$	10.6
Peak Diode Recovery dv/dt (Note 4)	dv/dt	4.5	V/ns
Power Dissipation	$P_D$	36	W
Junction Temperature	$T_J$	+150	$^\circ\text{C}$
Operating Temperature	$T_{OPR}$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating : Pulse width limited by maximum junction temperature

3.  $L = 30\text{mH}$ ,  $I_{AS} = 4\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\ \Omega$ , Starting  $T_J = 25^\circ\text{C}$

4.  $I_{SD} \leq 4.4\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$

■ THERMAL DATA

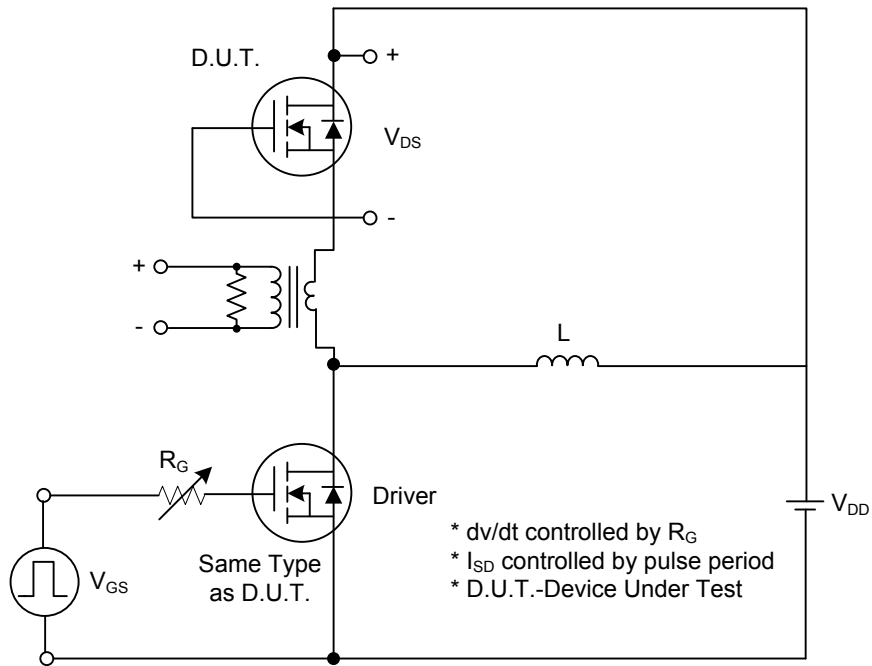
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	$\theta_{JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction to Case	$\theta_{Jc}$	3.47	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS (T<sub>C</sub>=25°C, unless otherwise specified)

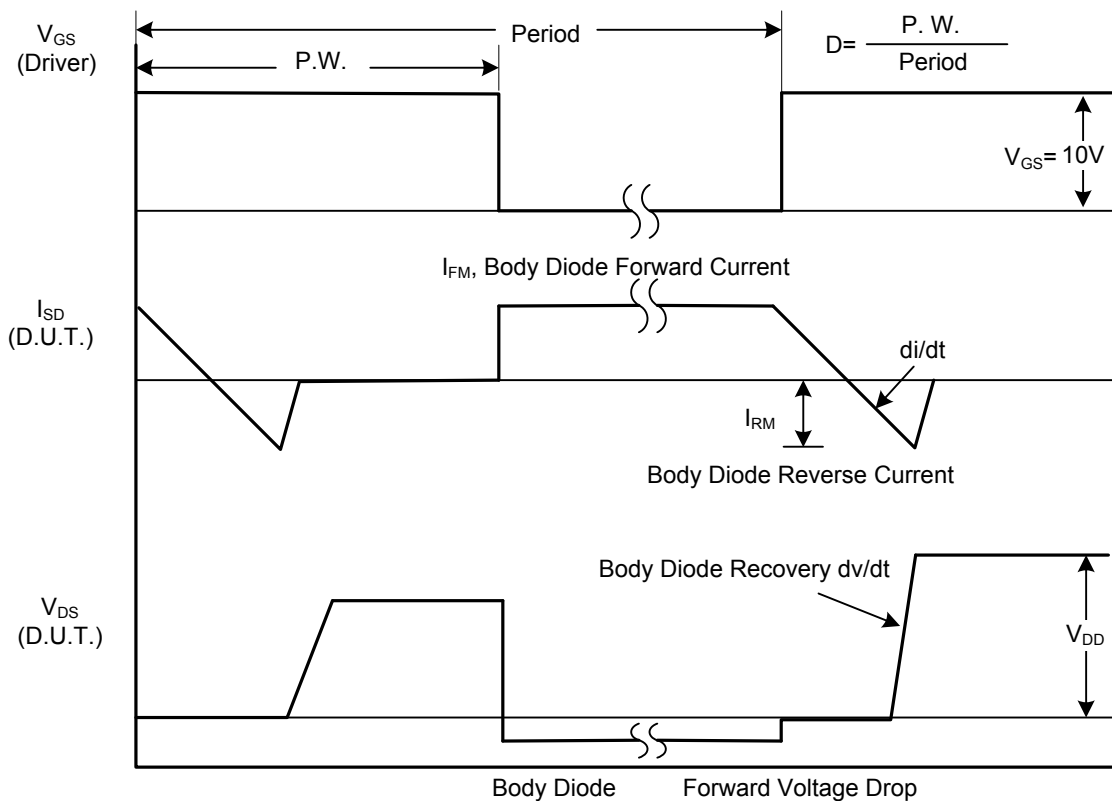
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250μA	650			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V			10	μA
Gate-Source Leakage Current	Forward	I <sub>GSS</sub>			100	nA
	Reverse				V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	
Breakdown Voltage Temperature Coefficient	ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	I <sub>D</sub> =250μA, Referenced to 25°C		0.6		V/°C
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.0		4.0	V
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.2A		2.4	2.5	Ω
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0V, f = 1MHz		520	670	pF
Output Capacitance	C <sub>OSS</sub>			70	90	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			8	11	pF
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> = 325V, I <sub>D</sub> = 4.0A, R <sub>G</sub> = 25Ω (Note 1, 2)		13	35	ns
Turn-On Rise Time	t <sub>R</sub>			45	100	ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			25	60	ns
Turn-Off Fall Time	t <sub>F</sub>			35	80	ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DS</sub> = 520V, I <sub>D</sub> = 4.0A, V <sub>GS</sub> = 10V (Note 1, 2)		15	20	nC
Gate-Source Charge	Q <sub>GS</sub>			3.4		nC
Gate-Drain Charge	Q <sub>GD</sub>			7.1		nC
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 4.4A			1.4	V
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>				4.4	A
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>				17.6	A
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 4.4A,		250		ns
Reverse Recovery Charge	Q <sub>RR</sub>	di <sub>F</sub> /dt = 100 A/μs (Note 1)		1.5		μC

Note: 1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%  
2. Essentially independent of operating temperature

## ■ TEST CIRCUITS AND WAVEFORMS

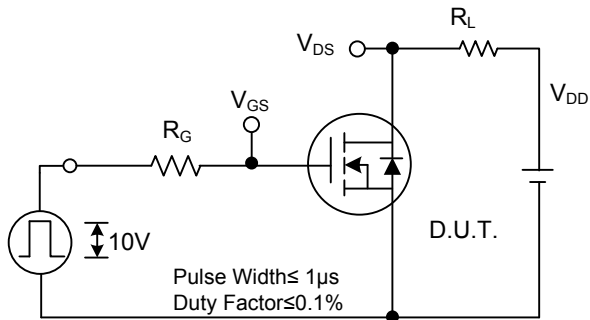


**Peak Diode Recovery  $dv/dt$  Test Circuit**

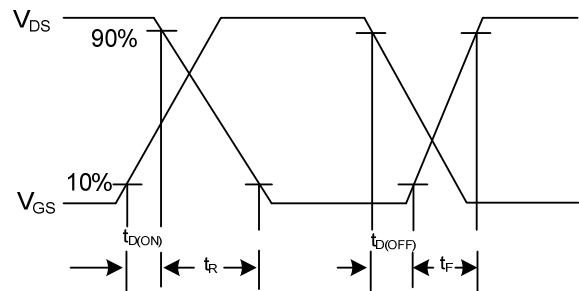


**Peak Diode Recovery  $dv/dt$  Waveforms**

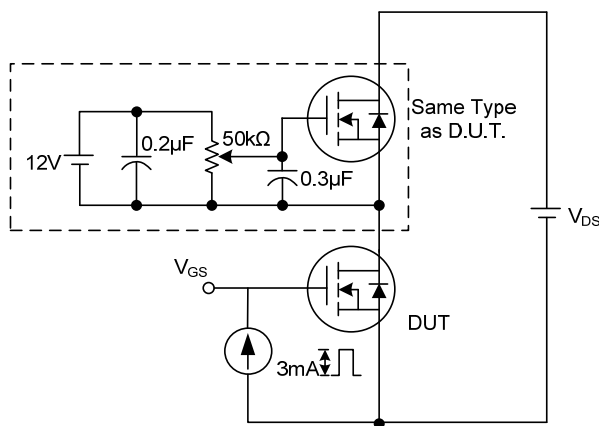
## TEST CIRCUITS AND WAVEFORMS (Cont.)



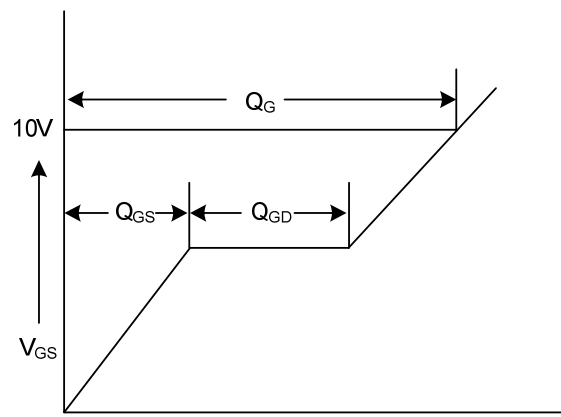
**Switching Test Circuit**



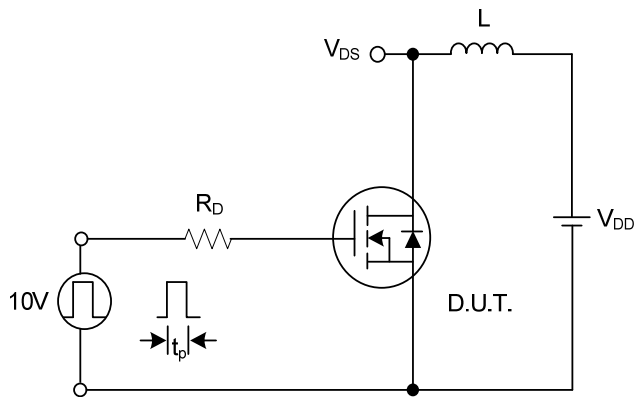
**Switching Waveforms**



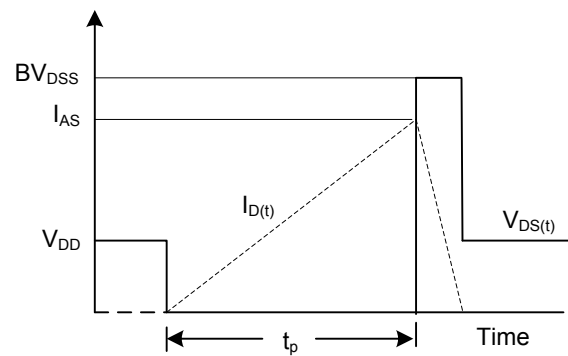
**Gate Charge Test Circuit**



**Gate Charge Waveform**

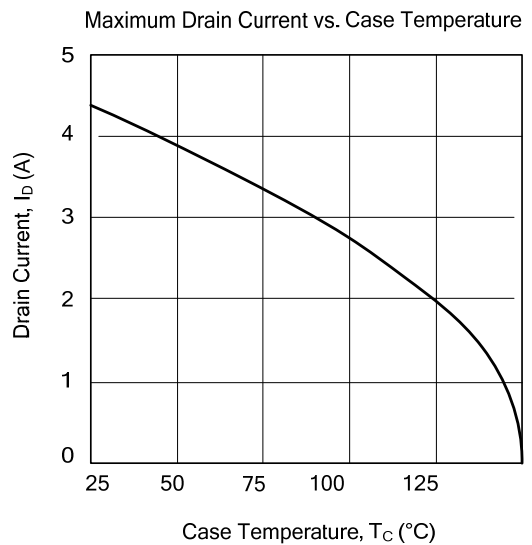
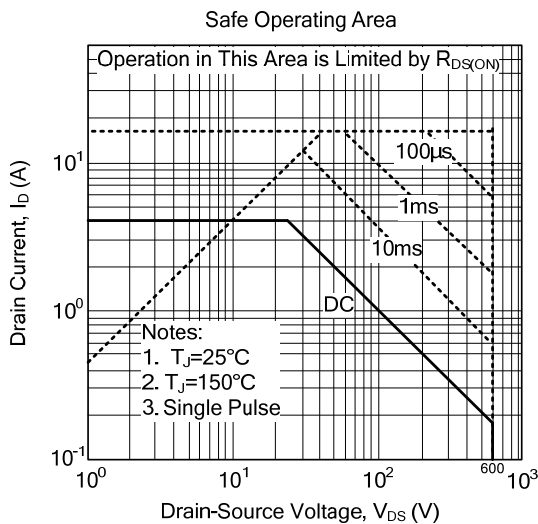
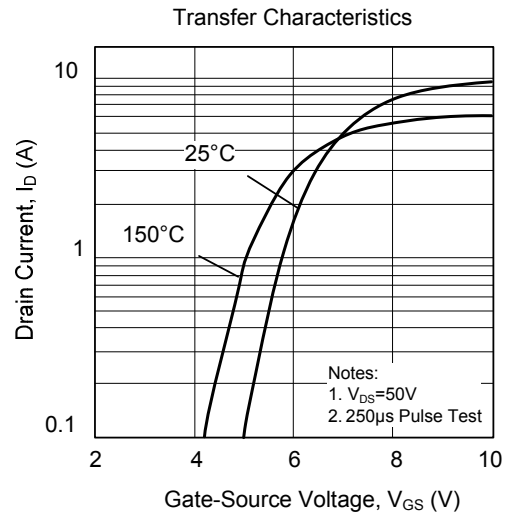
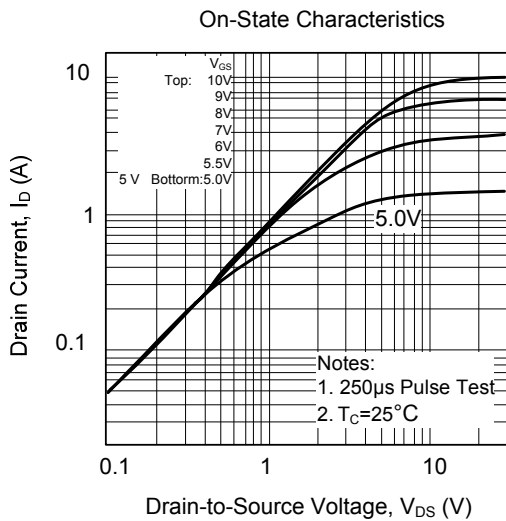
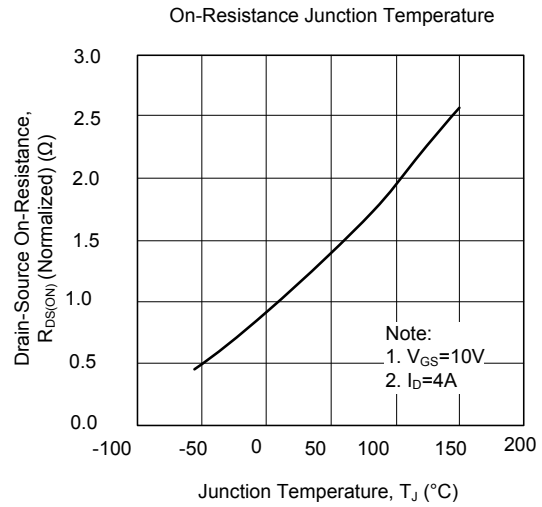
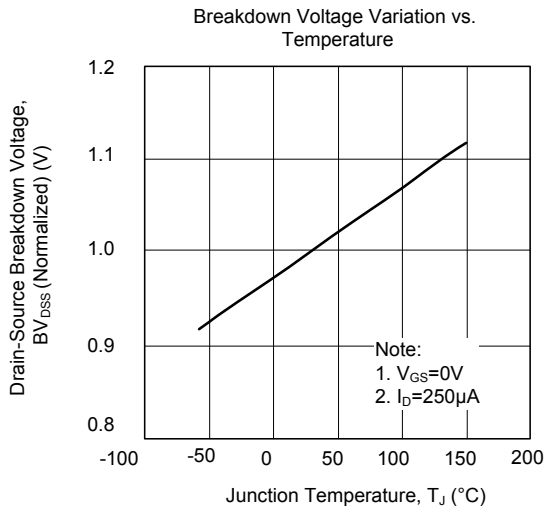


**Unclamped Inductive Switching Test Circuit**



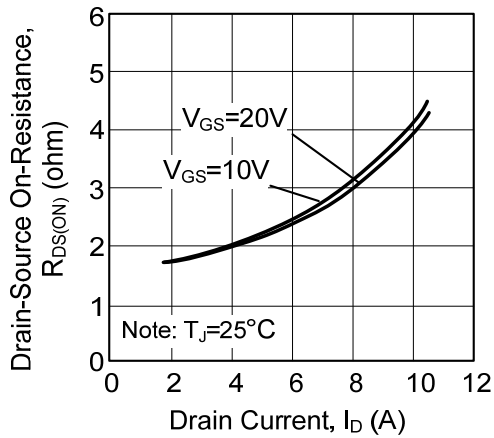
**Unclamped Inductive Switching Waveforms**

## TYPICAL CHARACTERISTICS

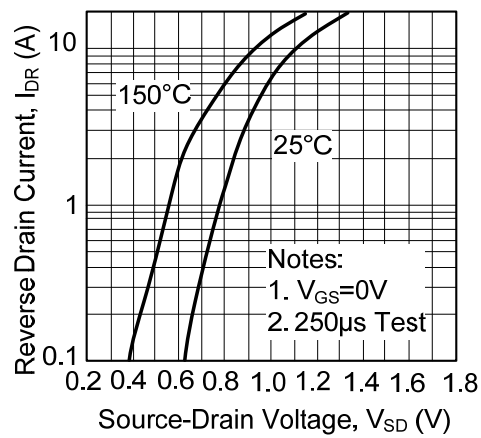


## ■ TYPICAL CHARACTERISTICS(Cont.)

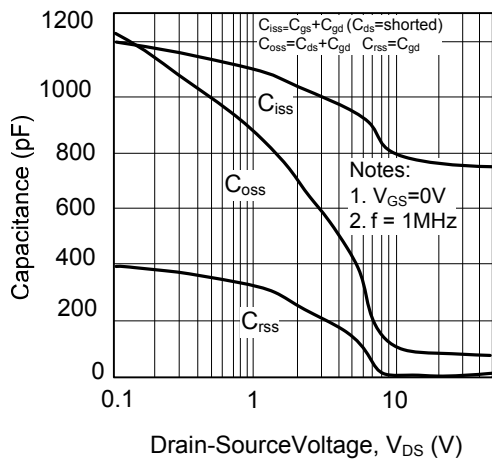
On-Resistance Variation vs. Drain Current and Gate Voltage



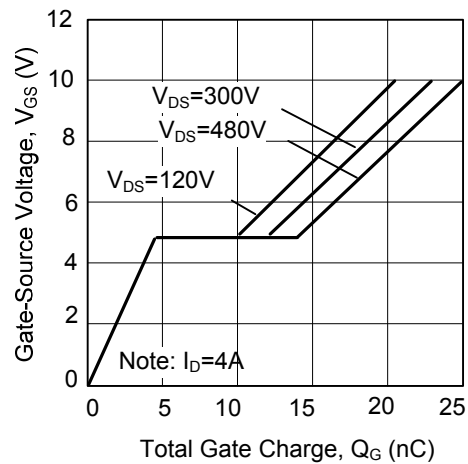
On State Current vs. Allowable Case Temperature



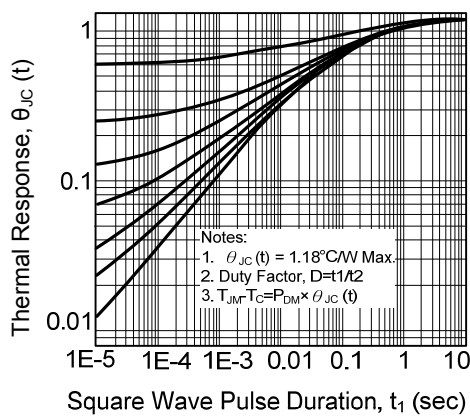
Capacitance Characteristics (Non-Repetitive)



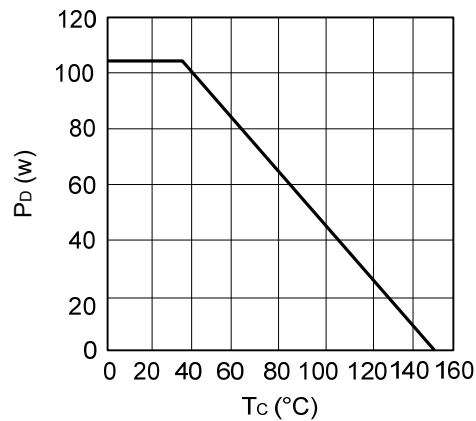
Gate Charge Characteristics



Transient Thermal Response Curve



Power Dissipation



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